

Advanced Techniques Applied

In order to meet the market trend and fast market change, we build our R&D team to control the reliability and stability of the products. We have been utilizing the advanced material and manufacturing techniques on producing the electronic elements and parts. In Taiwan, we are the first company to launch the Zinc Oxide (ZnO) based Ceramic Semiconductor devices with full range and with the highly advanced multilayer formation technologies to apply the high density circuit assemblies. We obtained many kinds of patents and awards for excellent product designs, and had been selected by government to attend the inter- national trade fair on behalf of Taiwan.

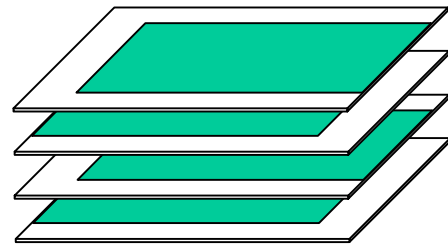
Major Additions and Improvements

Multilayer Surface Mount Transient Voltage Suppressors (TVS) are manufactured from semiconducting ceramics by the highly advanced multilayer formation technologies, which can offer rugged protection, excellent transient energy absorption and internal heat dissipation. The devices are leadless chip form, eliminating lead inductance and guaranteeing a faster speed of response time of less than 0.5ns, which makes them fast enough to ensure reliable protection against ESD pulse and other specific transient events. These transient suppression devices are significantly smaller footprints and lower profiles than traditional zener diodes or radial MOVs,

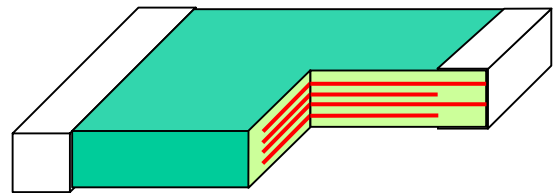
Electroplating

Now Varen provide electrode termination is Silver/Palladium.

Our Varen varistors and TVSs reliably protect the electronics systems from overvoltages by limiting surge voltages and by absorbing energy. They are used to safeguard the components, to ensure electromagnetic compatibility and to suppress the transients caused by electrostatic discharge. In other words they have the added advantage of greater surge current and energy handling capabilities as well as EMI/RFI attenuation. Varen varistors and TVSs have established themselves as a secure and low-cost means of protection in general-purpose use.



multilayer formation technologies



Section of the chip